

No-Clean Core Solder Wire FC5000/FC5005

In responding to a global call for green production technologies, we have applied the most advanced technology to produce no-clean core solder wire which allows no-clean process for welding and repairing.

Features

- Strong adhesion to many materials, appropriate for all forms of soldering
- No halides added, non-corrosive, no splash, no odor
- Less flux residue for shiny and clean solder spots
- Excellent wetting abilities
- No-clean technology saves time and labor for fast production or repairing

Specification

Composition, %	Sn/Pb 63/37	Sn/Pb 60/40
Melting point, °C	183	183 ~ 190
Specific gravity	8.4	8.5
Diameter, mm (inch)	3.0 (.114"), 2.5 (.098"), 2.0 (.079"), 1.6 (.063"), 1.2 (.047"), 1.0 (.04"), 0.8 (.032"), 0.6 (.023"), 0.5 (.02"), 0.3 (.0114")	
Package	0.1KG, 0.25KG, 0.5KG, 1KG	

Flux Classification

Item	FC5000	FC5005
Content of flux (Wt%)	2.0 ~ 2.2	2.0 ~ 2.5
Туре	RMA (ROL0)	RMA (ROL0)
Content of halides (Wt%)	Not added	Not added
Corrosion on Copper Plate	Passed	Passed
Aqueous solution resistant (Ω cm)	100,000 over	100,000 over
Insulation resistant (Ω)	1x10 ¹² over	1x10 ¹² over
Expansion (%)	90 over	90 over
Flux melting, °C	95	95
Residue view	Clear, minimal and dry	Clear, minimal and dry
Features	For precision soldering production and repairing with high reliability in no- clean processes	



Prokit's Industries Co., LTD.

5F., NO. 7, LN. 130, MINQUAN RD., XINDIAN DIST., NEW TAIPEI CITY 231023, TAIWAN TEL: +886 2 2218 3233 E-mail: pk@mail.prokits.com.tw